



Integrated  
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Systems, Inc.

**PRELIMINARY**

**ICS853011C**

Low SKEW, 1-TO-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

## GENERAL DESCRIPTION

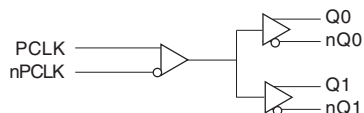


The ICS853011C is a low skew, high performance 1-to-2 Differential-to-2.5V/3.3V LVPECL/ECL Fanout Buffer and a member of the HiPerClockS™ family of High Performance Clock Solutions from ICS. The ICS853011C is characterized to operate from either a 2.5V or a 3.3V power supply. Guaranteed output and part-to-part skew characteristics make the ICS853011C ideal for those clock distribution applications demanding well defined performance and repeatability.

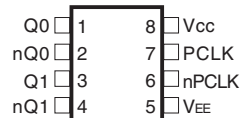
## FEATURES

- 2 differential 2.5V/3.3V LVPECL / ECL outputs
- 1 differential PCLK, nPCLK input pair
- PCLK, nPCLK pair can accept the following differential input levels: LVPECL, LVDS, CML, SSTL
- Output frequency: 3GHz
- Translates any single ended input signal to 3.3V LVPECL levels with resistor bias on nPCLK input
- Output skew: 5ps (typical)
- Part-to-part skew: TBD
- Propagation delay: 250ps (typical)
- LVPECL mode operating voltage supply range:  
 $V_{CC} = 2.375V$  to  $3.8V$ ,  $V_{EE} = 0V$
- ECL mode operating voltage supply range:  
 $V_{CC} = 0V$ ,  $V_{EE} = -3.8V$  to  $-2.375V$
- $-40^{\circ}C$  to  $85^{\circ}C$  ambient operating temperature
- Pin compatible with MC100LVEP11 and SY100EP11U

## BLOCK DIAGRAM



## PIN ASSIGNMENT



**ICS853011C**  
**8-Lead SOIC**

3.90mm x 4.90mm x 1.37mm package body

**M Package**  
Top View

**ICS853011C**  
**8-Lead TSSOP, 118 mil**

3mm x 3mm x 0.95mm package body

**G Package**  
Top View

The Preliminary Information presented herein represents a product in prototyping or pre-production. The noted characteristics are based on initial product characterization. Integrated Circuit Systems, Incorporated (ICS) reserves the right to change any circuitry or specifications without notice.



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**TABLE 1. PIN DESCRIPTIONS**

Number	Name	Type		Description
1, 2	Q0, nQ0	Output		Differential output pair. LVPECL interface levels.
3, 4	Q1, nQ1	Output		Differential output pair. LVPECL interface levels.
5	V <sub>EE</sub>	Power		Negative supply pin.
6	nPCLK	Input	Pullup/ Pulldown	Clock input. LVPECL interface levels.
7	PCLK	Input	Pulldown	Clock input. Default LOW when left floating. LVPECL interface levels.
8	V <sub>CC</sub>	Power		Positive supply pin.

NOTE: *Pullup and Pulldown* refer to internal input resistors. See Table 2, Pin Characteristics, for typical values.

**TABLE 2. PIN CHARACTERISTICS**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
R <sub>PULLDOWN</sub>	Input Pulldown Resistor			75		K $\Omega$
R <sub>PULLUP</sub>	Input Pullup Resistor			37		K $\Omega$



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# ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $V_{CC}$	4.6V (LVPECL mode, $V_{EE} = 0$ )
Negative Supply Voltage, $V_{EE}$	-4.6V (ECL mode, $V_{CC} = 0$ )
Inputs, $V_I$ (LVPECL mode)	-0.5V to $V_{CC} + 0.5V$
Inputs, $V_I$ (ECL mode)	0.5V to $V_{EE} - 0.5V$
Outputs, $I_O$	
Continuous Current	50mA
Surge Current	100mA
Operating Temperature Range, $T_A$	-40°C to +85°C
Storage Temperature, $T_{STG}$	-65°C to 150°C
Package Thermal Impedance, $\theta_{JA}$ (Junction-to-Ambient) for 8 Lead SOIC	112.7°C/W (0 lfm)
Package Thermal Impedance, $\theta_{JA}$ (Junction-to-Ambient) for 8 Lead TSSOP	101.7°C/W (0 m/s)

**NOTE:** Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These ratings are stress specifications only. Functional operation of product at these conditions or any conditions beyond those listed in the *DC Characteristics* or *AC Characteristics* is not implied. Exposure to absolute maximum rating conditions for extended periods may affect product reliability.

**TABLE 3A. POWER SUPPLY DC CHARACTERISTICS,  $V_{CC} = 2.375V$  TO  $3.8V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	Test Conditions	Minimum	Typical	Maximum	Units
$V_{CC}$	Positive Supply Voltage		2.375	3.3	3.8	V
$I_{EE}$	Power Supply Current			18		mA

**TABLE 3B. LVPECL DC CHARACTERISTICS,  $V_{CC} = 3.3V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1		2.275			2.295			2.295		V
$V_{OL}$	Output Low Voltage; NOTE 1		1.545			1.52			1.535		V
$V_{PP}$	Peak-to-Peak Input Voltage		800			800			800		V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3										V
$I_{IH}$	Input High Current	PCLK, nPCLK									μA
$I_{IL}$	Input Low Current	PCLK									μA
		nPCLK									μA

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with 50Ω to  $V_{CCO} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{CC} + 0.3V$ .



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**TABLE 3C. LVPECL DC CHARACTERISTICS,  $V_{CC} = 2.5V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1		1.475			1.495			1.495		V
$V_{OL}$	Output Low Voltage; NOTE 1		0.745			0.72			0.735		V
$V_{PP}$	Peak-to-Peak Input Voltage		800			800			800		V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3										V
$I_{IH}$	Input High Current	PCLK, nPCLK									$\mu A$
$I_{IL}$	Input Low Current	PCLK									$\mu A$
		nPCLK									$\mu A$

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CCO} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{CC} + 0.3V$ .

**TABLE 3D. ECL DC CHARACTERISTICS,  $V_{CC} = 0V$ ;  $V_{EE} = -3.8V$  TO  $-2.375V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$V_{OH}$	Output High Voltage; NOTE 1		-1.025			-1.005			-1.005		V
$V_{OL}$	Output Low Voltage; NOTE 1		-1.755			-1.78			-1.765		V
$V_{PP}$	Peak-to-Peak Input Voltage		800			800			800		V
$V_{CMR}$	Input High Voltage Common Mode Range; NOTE 2, 3										V
$I_{IH}$	Input High Current	PCLK, nPCLK									$\mu A$
$I_{IL}$	Input Low Current	PCLK									$\mu A$
		nPCLK									$\mu A$

Input and output parameters vary 1:1 with  $V_{CC}$ .  $V_{EE}$  can vary +0.925V to -0.5V.

NOTE 1: Outputs terminated with  $50\Omega$  to  $V_{CCO} - 2V$ .

NOTE 2: Common mode voltage is defined as  $V_{IH}$ .

NOTE 3: For single-ended applications, the maximum input voltage for PCLK, nPCLK is  $V_{CC} + 0.3V$ .

**TABLE 4. AC CHARACTERISTICS,  $V_{CC} = 0V$ ;  $V_{EE} = -3.8V$  TO  $-2.375V$  OR  $V_{CC} = 2.375$  TO  $3.8V$ ;  $V_{EE} = 0V$**

Symbol	Parameter	-40°C			25°C			85°C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
$f_{MAX}$	Output Frequency		3			3			3		GHz
$t_{PD}$	Propagation Delay; NOTE 1		240			250			260		ps
$t_{sk(o)}$	Output Skew; NOTE 2, 4		5			5			5		ps
$t_{sk(pp)}$	Part-to-Part Skew; NOTE 3, 4										ps
$t_R/t_F$	Output Rise/Fall Time	20% to 80%	160			160			160		ps
odc	Output Duty Cycle	$f \leq 1GHz$	50			50			50		%

All parameters are measured at  $f \leq 1.7GHz$ , unless otherwise noted.

NOTE 1: Measured from the differential input crossing point to the differential output crossing point.

NOTE 2: Defined as skew between outputs at the same supply voltage and with equal load conditions.

Measured at the output differential cross points.

NOTE 3: Defined as skew between outputs on different devices operating at the same supply voltages and with equal load conditions. Using the same type of inputs on each device, the outputs are measured at the differential cross points.

NOTE 4: This parameter is defined in accordance with JEDEC Standard 65.



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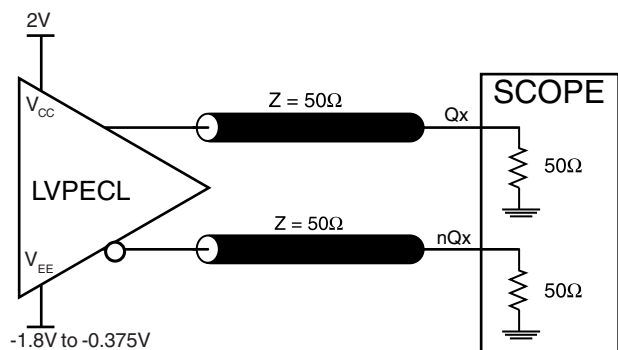
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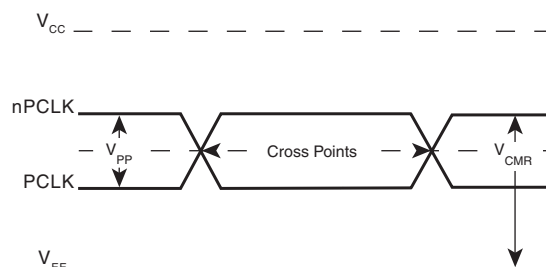
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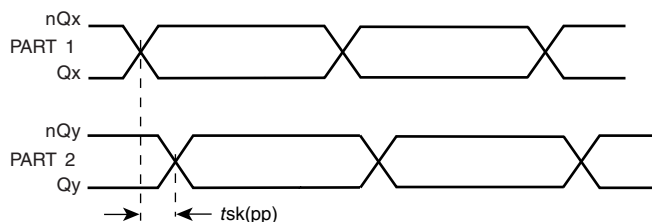
## PARAMETER MEASUREMENT INFORMATION



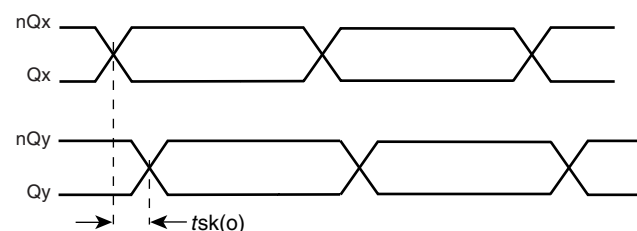
**OUTPUT LOAD AC TEST CIRCUIT**



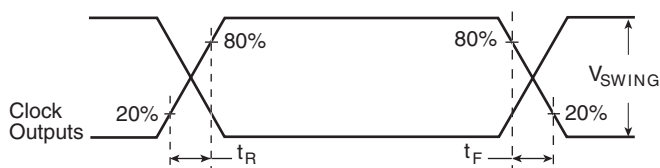
**DIFFERENTIAL INPUT LEVEL**



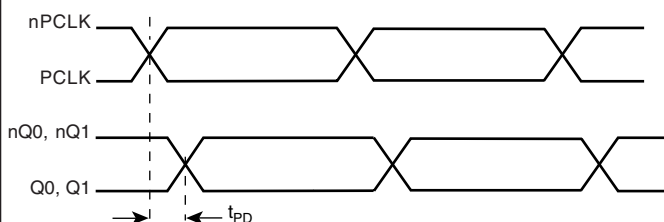
**PART-TO-PART SKEW**



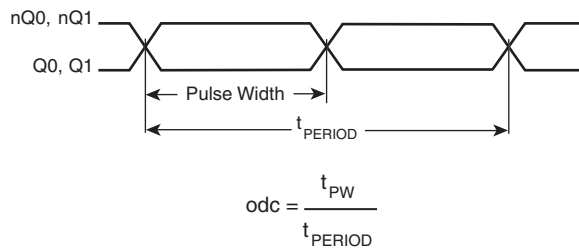
**OUTPUT SKEW**



**OUTPUT RISE/FALL TIME**



**PROPAGATION DELAY**



**OUTPUT DUTY CYCLE/PULSE WIDTH/PERIOD**



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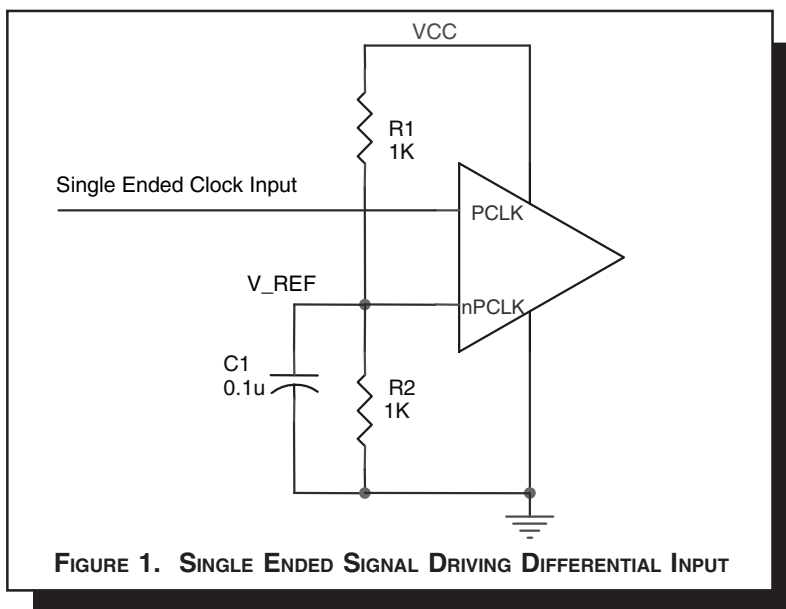
DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

## APPLICATION INFORMATION

### WIRING THE DIFFERENTIAL INPUT TO ACCEPT SINGLE ENDED LEVELS

Figure 1 shows how the differential input can be wired to accept single ended levels. The reference voltage  $V_{REF} = V_{CC}/2$  is generated by the bias resistors R1, R2 and C1. This bias circuit should be located as close as possible to the input pin. The ratio

of R1 and R2 might need to be adjusted to position the  $V_{REF}$  in the center of the input voltage swing. For example, if the input clock swing is only 2.5V and  $V_{CC} = 3.3V$ ,  $V_{REF}$  should be 1.25V and  $R2/R1 = 0.609$ .

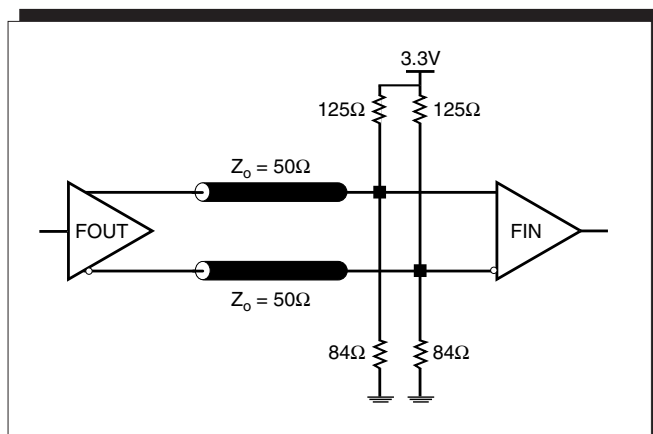
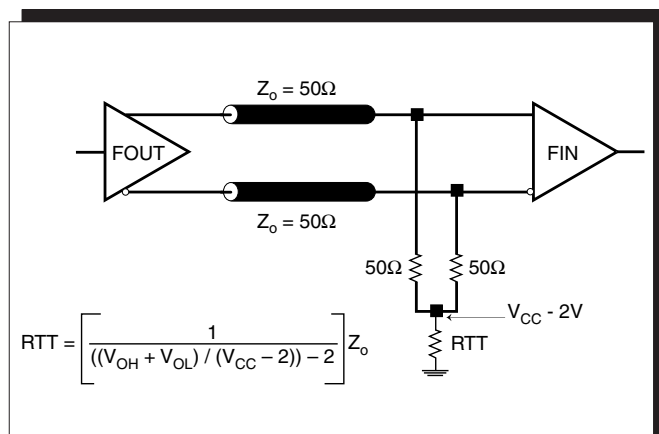


### TERMINATION FOR 3.3V LVPECL OUTPUTS

The clock layout topology shown below is a typical termination for LVPECL outputs. The two different layouts mentioned are recommended only as guidelines.

FOUT and nFOUT are low impedance follower outputs that generate ECL/LVPECL compatible outputs. Therefore, terminating resistors (DC current path to ground) or current sources must be used for functionality. These outputs are designed to drive

50Ω transmission lines. Matched impedance techniques should be used to maximize operating frequency and minimize signal distortion. Figures 2A and 2B show two different layouts which are recommended only as guidelines. Other suitable clock layouts may exist and it would be recommended that the board designers simulate to guarantee compatibility across all printed circuit and clock component process variations.





### TERMINATION FOR 2.5V LVPECL OUTPUT

Figure 3A and Figure 3B show examples of termination for 2.5V LVPECL driver. These terminations are equivalent to terminating  $50\Omega$  to  $V_{CC} - 2V$ . For  $V_{CC} = 2.5V$ , the  $V_{CC} - 2V$  is very close to

ground level. The R3 in Figure 3B can be eliminated and the termination is shown in Figure 3C.

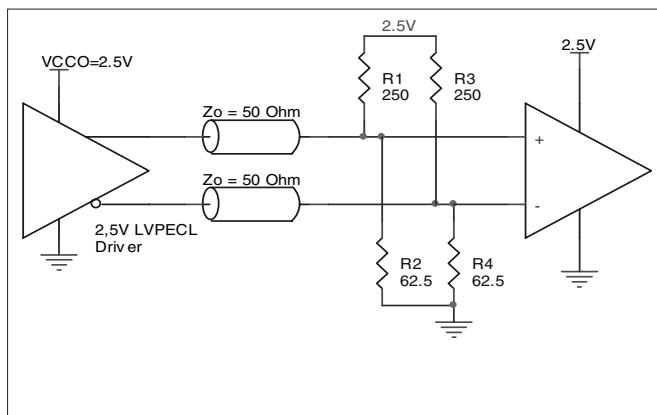


FIGURE 3A. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

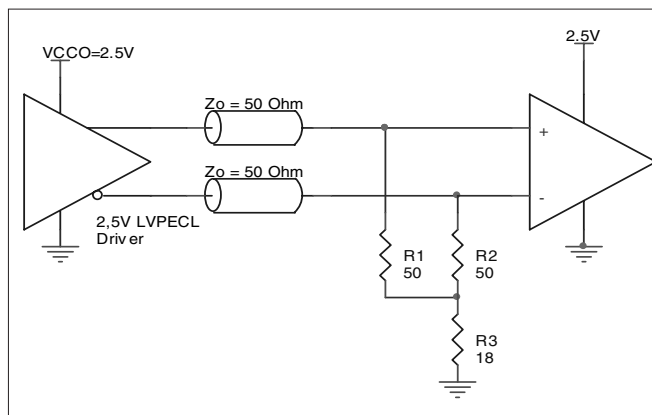


FIGURE 3B. 2.5V LVPECL DRIVER TERMINATION EXAMPLE

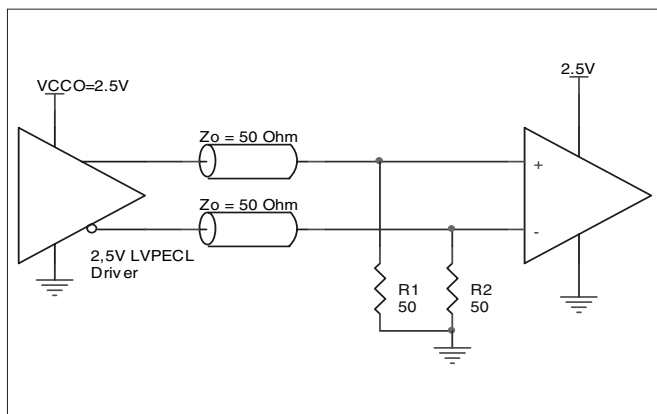


FIGURE 3C. 2.5V LVPECL TERMINATION EXAMPLE



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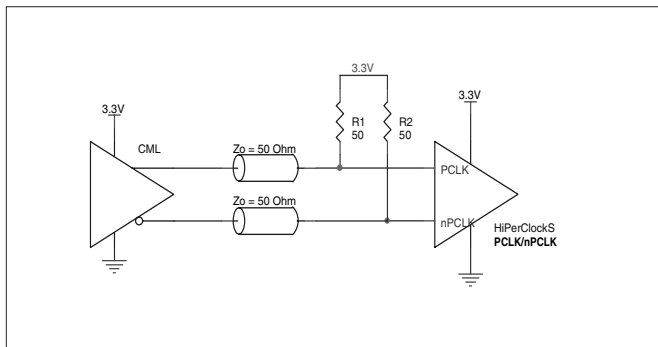
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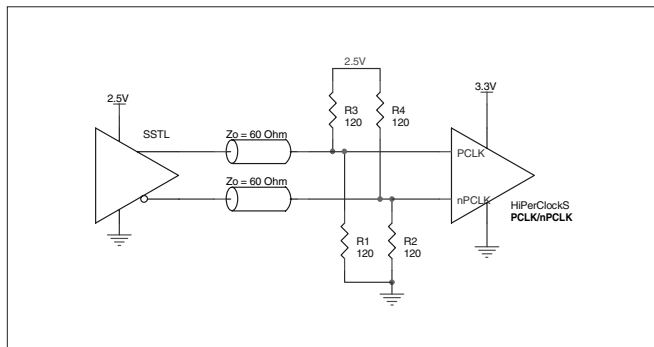
## LVPECL CLOCK INPUT INTERFACE

The PCLK /nPCLK accepts LVPECL, CML, SSTL and other differential signals. Both  $V_{\text{SWING}}$  and  $V_{\text{OH}}$  must meet the  $V_{\text{PP}}$  and  $V_{\text{CMR}}$  input requirements. Figures 4A to 4E show interface examples for the HiPerClockS PCLK/nPCLK input driven by the most common driver types. The input interfaces suggested

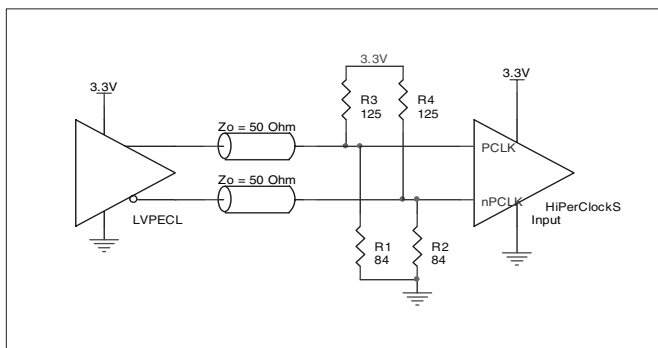
here are examples only. If the driver is from another vendor, use their termination recommendation. Please consult with the vendor of the driver component to confirm the driver termination requirements.



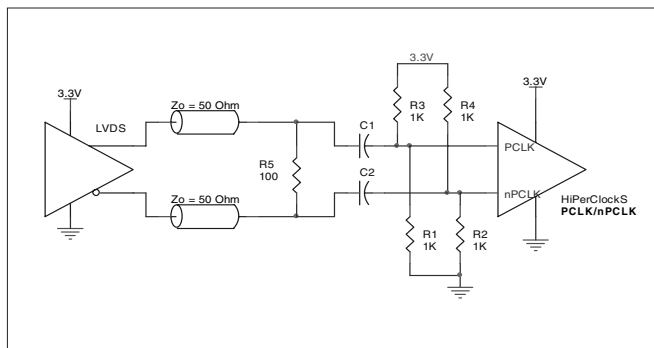
**FIGURE 4A. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A CML DRIVER**



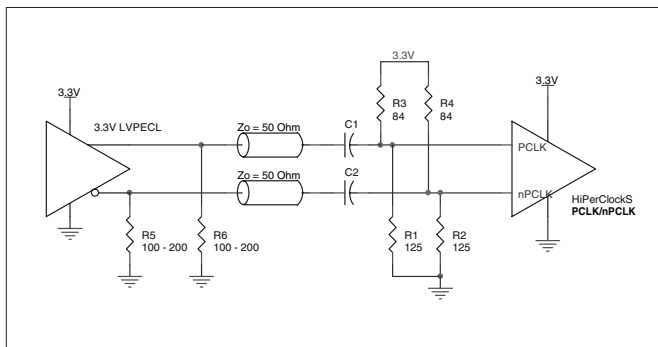
**FIGURE 4B. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY AN SSTL DRIVER**



**FIGURE 4C. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER**



**FIGURE 4D. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVDS DRIVER**



**FIGURE 4E. HiPerClockS PCLK/nPCLK INPUT DRIVEN BY A 3.3V LVPECL DRIVER WITH AC COUPLE**





## POWER CONSIDERATIONS

This section provides information on power dissipation and junction temperature for the ICS853011C. Equations and example calculations are also provided.

### 1. Power Dissipation.

The total power dissipation for the ICS853011C is the sum of the core power plus the power dissipated in the load(s). The following is the power dissipation for  $V_{CC} = 3.8V$ , which gives worst case results.

**NOTE:** Please refer to Section 3 for details on calculating power dissipated in the load.

- Power (core)<sub>MAX</sub> =  $V_{CC\_MAX} * I_{EE\_MAX} = 3.8V * 18mA = 68.4mW$
- Power (outputs)<sub>MAX</sub> = **30.94mW/Loaded Output pair**  
If all outputs are loaded, the total power is  $2 * 30.94mW = 61.88mW$

**Total Power**<sub>MAX</sub> (3.8V, with all outputs switching) =  $68.4mW + 61.88mW = 130.3mW$

### 2. Junction Temperature.

Junction temperature,  $T_j$ , is the temperature at the junction of the bond wire and bond pad and directly affects the reliability of the device. The maximum recommended junction temperature for HiPerClockS™ devices is 125°C.

The equation for  $T_j$  is as follows:  $T_j = \theta_{JA} * Pd\_total + T_A$

$T_j$  = Junction Temperature

$\theta_{JA}$  = Junction-to-Ambient Thermal Resistance

$Pd\_total$  = Total Device Power Dissipation (example calculation is in section 1 above)

$T_A$  = Ambient Temperature

In order to calculate junction temperature, the appropriate junction-to-ambient thermal resistance  $\theta_{JA}$  must be used. Assuming a moderate air flow of 200 linear feet per minute and a multi-layer board, the appropriate value is 103.3°C/W per Table 5A below.

Therefore,  $T_j$  for an ambient temperature of 85°C with all outputs switching is:

$85^\circ C + 0.130W * 103.3^\circ C/W = 98.4^\circ C$ . This is well below the limit of 125°C.

This calculation is only an example.  $T_j$  will obviously vary depending on the number of loaded outputs, supply voltage, air flow, and the type of board (single layer or multi-layer).

**TABLE 5A. THERMAL RESISTANCE  $\theta_{JA}$  FOR 8-PIN SOIC, FORCED CONVECTION**

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W
<b>NOTE:</b> Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			

**TABLE 5B. THERMAL RESISTANCE  $\theta_{JA}$  FOR 8-PIN TSSOP, FORCED CONVECTION**

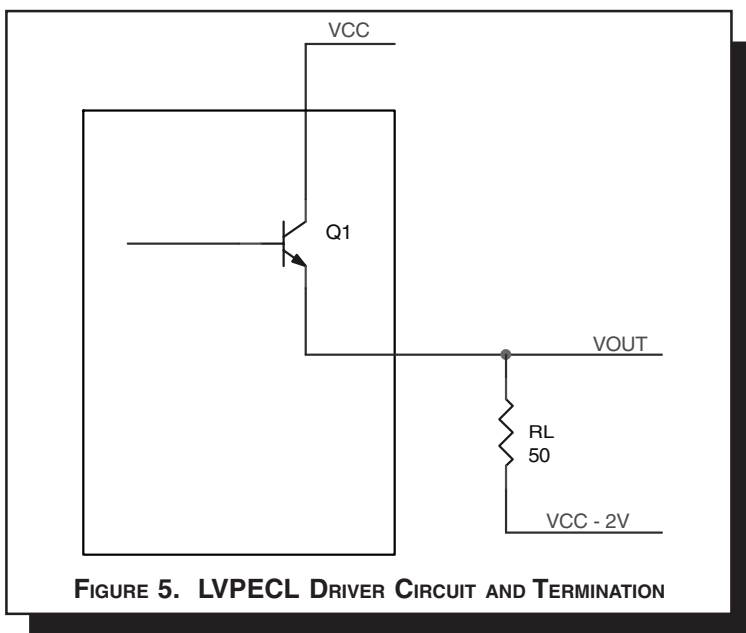
$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W



### 3. Calculations and Equations.

The purpose of this section is to derive the power dissipated into the load.

LVPECL output driver circuit and termination are shown in *Figure 5*.



To calculate worst case power dissipation into the load, use the following equations which assume a 50Ω load, and a termination voltage of  $V_{CC} - 2V$ .

- For logic high,  $V_{OUT} = V_{OH\_MAX} = V_{CC\_MAX} - 0.935V$

$$(V_{CC\_MAX} - V_{OH\_MAX}) = 0.935V$$

- For logic low,  $V_{OUT} = V_{OL\_MAX} = V_{CC\_MAX} - 1.67V$

$$(V_{CC\_MAX} - V_{OL\_MAX}) = 1.67V$$

$Pd\_H$  is power dissipation when the output drives high.

$Pd\_L$  is the power dissipation when the output drives low.

$$Pd\_H = [(V_{OH\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OH\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OH\_MAX}) = [(2V - 0.935V)/50\Omega] * 0.935V = 19.92mW$$

$$Pd\_L = [(V_{OL\_MAX} - (V_{CC\_MAX} - 2V))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - (V_{CC\_MAX} - V_{OL\_MAX}))/R_L] * (V_{CC\_MAX} - V_{OL\_MAX}) = [(2V - 1.67V)/50\Omega] * 1.67V = 11.02mW$$

$$\text{Total Power Dissipation per output pair} = Pd\_H + Pd\_L = 30.94mW$$



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## RELIABILITY INFORMATION

**TABLE 6A.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD SOIC**

$\theta_{JA}$ by Velocity (Linear Feet per Minute)			
	0	200	500
Single-Layer PCB, JEDEC Standard Test Boards	153.3°C/W	128.5°C/W	115.5°C/W
Multi-Layer PCB, JEDEC Standard Test Boards	112.7°C/W	103.3°C/W	97.1°C/W
<b>NOTE:</b> Most modern PCB designs use multi-layered boards. The data in the second row pertains to most designs.			

**TABLE 6B.  $\theta_{JA}$  VS. AIR FLOW TABLE FOR 8 LEAD TSSOP**

$\theta_{JA}$ by Velocity (Meters per Second)			
	0	1	2
Multi-Layer PCB, JEDEC Standard Test Boards	101.7°C/W	90.5°C/W	89.8°C/W

### TRANSISTOR COUNT

The transistor count for ICS853011C is: 96



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PACKAGE OUTLINE - M SUFFIX FOR 8 LEAD SOIC

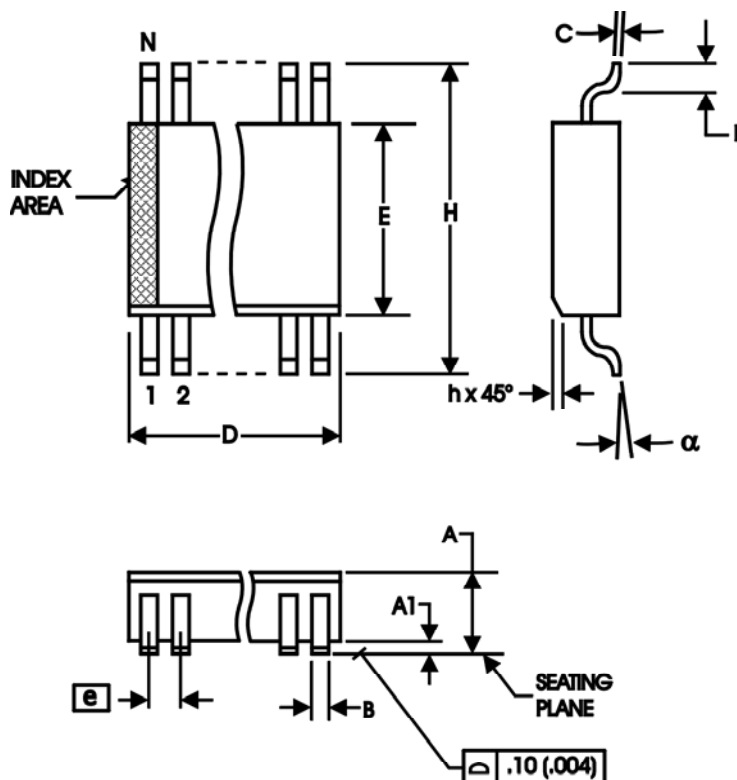


TABLE 7A. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	MINIMUM	MAXIMUM
N	8	
A	1.35	1.75
A1	0.10	0.25
B	0.33	0.51
C	0.19	0.25
D	4.80	5.00
E	3.80	4.00
e	1.27 BASIC	
H	5.80	6.20
h	0.25	0.50
L	0.40	1.27
α	0°	8°

Reference Document: JEDEC Publication 95, MS-012



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**PRELIMINARY**

**ICS853011C**

LOW SKEW, 1-TO-2

DIFFERENTIAL-TO-2.5V/3.3V LVPECL/ECL FANOUT BUFFER

PACKAGE OUTLINE - G SUFFIX FOR 8 LEAD TSSOP

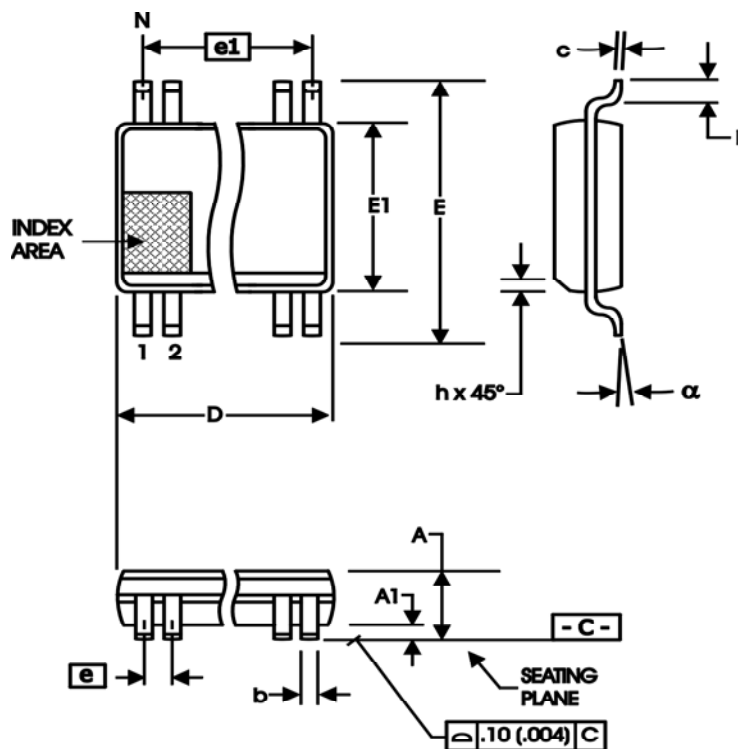


TABLE 7B. PACKAGE DIMENSIONS

SYMBOL	Millimeters	
	Minimum	Maximum
N	8	
A	--	1.10
A1	0	0.15
A2	0.79	0.97
b	0.22	0.38
c	0.08	0.23
D	3.00 BASIC	
E	4.90 BASIC	
E1	3.00 BASIC	
e	0.65 BASIC	
e1	1.95 BASIC	
L	0.40	0.80
$\alpha$	0°	8°
aaa	--	0.10

Reference Document: JEDEC Publication 95, MO-187



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**TABLE 8. ORDERING INFORMATION**

Part/Order Number	Marking	Package	Count	Temperature
ICS853011CM	853011C	8 lead SOIC	96 per tube	-40°C to 85°C
ICS853011CMT	853011C	8 lead SOIC on Tape and Reel	2500	-40°C to 85°C
ICS853011CMLF	3011CLF	"Lead Free" 8 lead SOIC	96 per tube	-40°C to 85°C
ICS853011CMLFT	3011CLF	"Lead Free" 8 lead SOIC on Tape and Reel	2500	-40°C to 85°C
ICS853011CG	011C	8 lead TSSOP	96 per tube	-40°C to 85°C
ICS853011CGT	011C	8 lead TSSOP on Tape and Reel	2500	-40°C to 85°C

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